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(71) Applicant: **VERSUM MATERIALS US, LLC** [US/US];
8555 S. River Parkway, Tempe, Arizona 85284 (US).

(72) Inventors: **WANG, Lili**; 8555 S. River Parkway, Tempe, AZ 85284 (US). **WU, Aiping**; 8555 S. River Parkway, Tempe, AZ 85284 (US). **SUN, Laisheng**; 8555 S. River Parkway, Tempe, AZ 85284 (US). **LEE, Yi-Chia**; 8555 S. River Parkway, Tempe, AZ 85284 (US). **CAO, Yuanmei**; 8555 S. River Parkway, Tempe, AZ 85284 (US).

(74) Agent: **ROSSI, Joseph D.** et al.; Stradley Ronon Stevens & Young, LLP, 30 Valley Stream Parkway, Great Valley Corporate Center, Malvern, PA 19355 (US).

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(54) Title: CLEANING COMPOSITION FOR SEMICONDUCTOR SUBSTRATES

(57) Abstract: Compositions and methods useful for removing residue and photoresist from a semiconductor substrate comprising: from about 5 to about 60% by wt. of water; from about 10 to about 90% by wt. of a water-miscible organic solvent; from about 5 to about 90% by wt. of at least one alkanolamine; from about 0.05 to about 20% by wt. of at least one polyfunctional organic acid; and from about 0.1 to about 10% by wt. of at least one phenol-type corrosion inhibitor, wherein the composition is substantially free of hydroxylamine.



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